瀚荃股份有限公司
CviLux Corporation

General Plating

TABLE- 1 (Tin-Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
1	30 μ" Tin Min.	Reflow Plated	Overall	Crimp clip terminal
	80 μ" Tin Min.	30 μ" Nickel Min.	Overall	Crimp clip terminal
	100 μ" Tin Min.	30 μ Nickel Min.	Overall	Solder tail terminal & Board in terminal
	120 μ" Tin Min.	30 μ Nickel Min.	Overall	Square or round pin
	120 μ" Tin	50 μ Nickel Min.	Overall	SMT type terminal

TABLE- 2 (Gold -Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
2	0.8 μ" Gold Min.	50 μ" Nickel Min.	Overall	Square or round pin
	1.2 μ" Gold Min.			Other type
3	15 μ" Gold Min.	50 μ" Nickel	Overall	All type
4	30 μ" Gold Min.	50 μ" Nickel	Overall	All type
5	50 μ" Gold Min.	50 μ" Nickel	Overall	All type
7	3 μ" Gold Min.	50 μ" Nickel	Overall	All type
8	80 μ" Gold Plated over	50 μ" Nickel	Overall	CP35
9	5 μ" Gold Plated over	50 μ" Nickel	Overall	All type
A	Selective 1.2 μ" Gold Flash	50 μ" Nickel	Contact Area	All type
B	Selective 15 μ" Gold	50 μ" Nickel	Contact Area	All type
C	Selective 30 μ" Gold	50 μ" Nickel	Contact Area	All type

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General Plating

D	Selective 10μ" Gold	50μ" Nickel	Contact Area	All type
E	Selective 50μ" Gold	50μ" Nickel	Contact Area	All type
F	Selective 80μ" Gold	50μ" Nickel	Contact Area	CP35
G	Selective 5μ" Gold	50μ" Nickel	Contact Area	CCF
I	Selective 15μ" Gold	1.2μ" Gold Flash Plated over 50μ" Nickel	Contact Area	All type
J	Selective 30μ" Gold	1.2μ" Gold Flash Plated over 50μ" Nickel	Contact Area	All type
K	Selective 5μ" Gold	80μ" Nickel	Contact Area	All type

SOLDERABILITY:

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solderability	Soldering time: 5±0.5 Second Soldering pot: 230±5℃	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3±0.5 Second Soldering pot: 245±5℃	Lead Free Process	